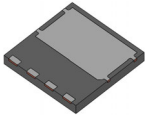


# MECHANICAL CASE OUTLINE

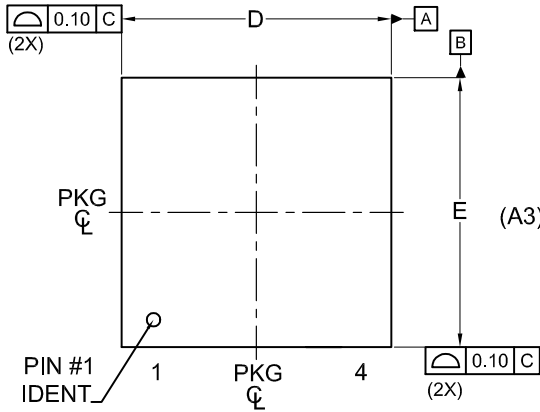
## PACKAGE DIMENSIONS

ON Semiconductor®



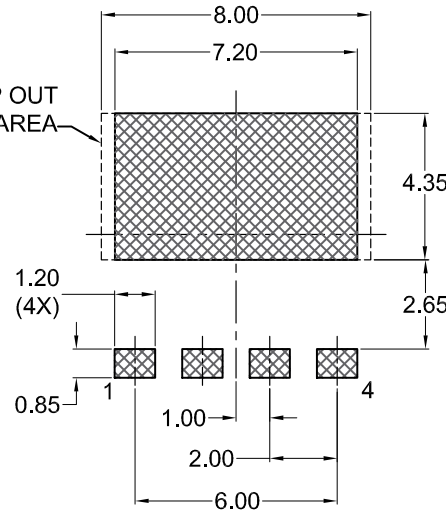
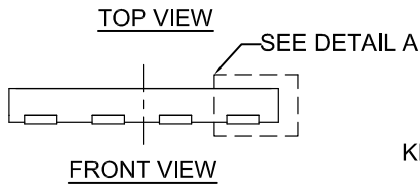
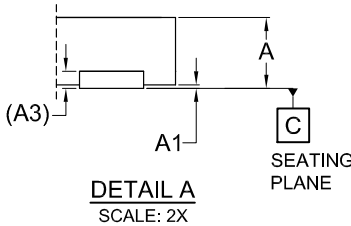
**PQFN4 8X8, 2P**  
CASE 483AP  
ISSUE A

DATE 06 JUL 2021



**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
6. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.



| DIM | MILLIMETERS |      |      |
|-----|-------------|------|------|
|     | MIN.        | NOM. | MAX. |
| A   | 0.90        | 1.00 | 1.10 |
| A1  | 0.00        | -    | 0.05 |
| A3  | 0.20 REF    |      |      |
| b   | 0.90        | 1.00 | 1.10 |
| D   | 7.90        | 8.00 | 8.10 |
| D2  | 7.10        | 7.20 | 7.30 |
| D3  | 0.40 REF    |      |      |
| E   | 7.90        | 8.00 | 8.10 |
| E2  | 4.25        | 4.35 | 4.45 |
| E3  | 0.25        | 0.35 | 0.45 |
| E4  | 0.40 REF    |      |      |
| e   | 2.00 BSC    |      |      |
| e/2 | 1.00 BSC    |      |      |
| e1  | 3.10 BSC    |      |      |
| e2  | 0.17 BSC    |      |      |
| k   | 2.75 REF    |      |      |
| L   | 0.40        | 0.50 | 0.60 |

**LAND PATTERN RECOMMENDATION**

\*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

|                         |                      |  |
|-------------------------|----------------------|--|
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